



features

- Adjustment processes are decreased by function and ratio trimmings
- High density mounting by bonding (COB)
- Various types of package are available
- High reliability achieved by KOAs original thick film technology
- Thick film printed circuit substrate applies the non-noble metal paste (conductive paste and resistive paste) and receives the many total inquires including material selecting, pattern designing and mass production

ordering information

KA	7777	D
Product Code	KOA Ref. Number	Terminal Surface Material
KA: Hybrid IC		D: SnAgCu T: Sn

Component - KA Series

Substrate Materials	Item	Printing	Mounting	Bonding
	Al ₂ O ₃ Alumina	o	o	o
	Glass epoxy	x	o	o
Conductors, Resistors	Item	Ag-Pd	Ag-Pt	
	Conductor resistance	18mΩ/□/15μm	5mΩ/□/10μm	
	Heat shock	-55°C~+125°C 300 Cycles	-55°C~+125°C 500 Cycles	
	RuO ₂	5Ω~10MΩ ±100x10 ⁶ /K		
Mounting	Item	Specifications		
	COB	Au Wire, Al Wire		
	BGA	0.5mm Pitch~		
	QFP	0.4mm Pitch~		
	Chip	0.4mm x 0.2mm		
Package, Outside Terminals	Package	Lead Pitch		
	SIP	1.8mm, 2.0mm, 2.5mm, 2.54mm		
	DIP, SOP	1.27mm, 1.8mm, 2.54mm		
	ZIP	2.54mm		
	BGA, LGA	1.0mm~		
Over Coating, Plating	Over Coating	Color	UL Standard	
	Epoxy metamorphic phenol	Black	94 V0 Approved	
	Epoxy	Black	94 V1 Approved	

o= Available x= Not available